# PRODUCT: Jack PCTM EFI 6700 Thin-Client

# A. SYSTEM DIMENSIONS AND WEIGHT

Configuration	Depth, cm	Width, cm	Height, cm	Weight, kg
With decorative frame	3.6	8.6	8.6	0.25
Without decorative frame	3.6	5.8	5.8	0.35

#### **B. DECLARATIONS AND CERTIFICATIONS**

#### **B1. REGULATORY COMPLIANCE INFORMATION**

This system received the following approvals and may be labeled with one or more of these marks depending on point of purchase:

Approvals	Certificate #/Standard	Yes / No / N/A
Energy Saving		
USA: Energy Star Compliance	N/A	Yes
EMC/EMI (Electro-Magnetic C	ompliance/Interference):	
European EU – CE Mark	EN55022 Class B, EN61000-3-2/3, EN55024 CISPR 22:1997 Class A Radiated, Power line Conducted EN 50081-1:1992 Emissions - Residential, Commercial EN 55022:1998 Class A Radiated, Power line Conducted EN 61000-3-2:1995 Power Line Conducted Emissions EN 61000-3-3:1995 Power Line Fluctuation and Flicker EN 55024:1998 Immunity - Information Technology Equipment EN 61000-4-2:1995 Electro-Static-Discharge (ESD) EN 61000-4-3:1997 Radiated Susceptibility EN 61000-4-4:1995 Electrical Fast Transient Burst	Yes
USA - FCC Mark	47CFR FCC Part 15, Subpart B:2003 Class B Commercial Equipment	Yes
Japan - VCCI Mark	N/A	Yes
Safety		•
European EU	EN/IEC 60950-1:2001 Safety for Information Technology Equipment	Yes
USA & Canada - cUL	UL/cUL 60950-1:2003 Safety for Information Technology Equipment (UL File # E17001)	Yes

# **B2. US FCC INFORMATION**

This product has been tested and found to comply with the limits for a Class B digital device pursuant to Part 15 of the FCC rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment.



This product generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications.

Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at their own expense.

Note: This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions:

- 1. This device may not cause harmful interference.
- 2. This device must accept any interference received, including interference that may cause undesired operation.

CAUTION: If you make any modification to the equipment not expressly approved by DTI, you could void your authority to operate the equipment.

# C. PERFORMANCE DATA

#### **C1. ELECTROMAGNETIC COMPATIBILITY**

Systems marked with the symbol "CE" indicate compliance to the EMC Directive and the Low Voltage Directive of the European Union.

#### **C2. SYSTEM CONFIGURATION**

The Energy Consumption and Declared Noise Emissions data is based on a device running the highest resolution and color depth setting, in 100BaseT full duplex network with ICA session presenting graphic intensive screen saver. Standard USB optical mouse and USB keyboard connected.

## D. ENERGY CONSUMPTION

Service Level	Energy Consumption (Wattage)	Heat Dissipation (BTU/hr)	Description of Service Level	Energy Save Requirements Meets EU ECO label (2001/686/EC and 2001/687/EC) Yes / No / N/A
*Maximum	6.00	13.6	The system is running programs to maximize the power consumption	N/A
Minimum	2.8	8.9	The system is in a waiting mode, such as at the local desktop no session is running	N/A
ACPI S3	0.6	2	The system is in a low -power/sleep mode	Yes
Off (standby)	0.6	2	The system is turned off but is still connected to its power source	Yes

Energy consumption is tested at 230 Volts / 50 Hz. Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour. Off data is not meant to show compliance to US Executive Order 13221.

<sup>&</sup>lt;sup>1</sup> This document is informational only and reflects laboratory performance. Your product may perform differently, depending on the software, components and peripherals you operate. Accordingly, the customer should not rely upon this information in making decisions about electrical tolerances or otherwise. No warranty as to accuracy or completeness is expressed or implied. The information in this document may change without notice; please note the revision number on the last page.

<sup>\*</sup>Maximum Energy Consumption results are based solely upon the testing of the System Configuration listed above.



#### E. DECLARED NOISE EMISSIONS IN ACCORDANCE WITH ISO 9296

Service Level	Sound Power (L <sub>WAd</sub> , bels) (1 bel=10 decibels, re 10 <sup>-12</sup> Watts)	Sound Pressure Operator Position (L <sub>pAm</sub> , decibels) (re 2x10 <sup>-5</sup> Pa)	
Inside active ICA session	0.00	0.00	
ldle – local desktop	0.00	0.00	

# F. PRODUCT MATERIALS INFORMATION

#### F1. RESTRICTED SUBSTANCES

This Chip PC product (plastic case parts, printed wiring boards, power supplies, and microprocessors) does NOT contain any of the following substances (in concentrations exceeding natural background levels)

- Asbestos
- Cadmium and its compounds above 100 parts per million (ppm)
- Halogenated dioxins or furans (i.e. polychlorinated dibenzodioxines, polychlorinated dibenzofurans)
- Halogenated flame retardants (chlorinated, brominated) in plastic parts over 25g
- Mercury (except for fluorescent bulbs used in display units)
- PCBs (polychlorobiphenyls) or PCTs (polychloroterphenyls)
- PBBs (polybromobiphenyls) or PBDEs (polybrominated diphenylethers)
- PVC (polyvinyl chloride) other than in cables and interconnect parts
- CFCs (chlorofluorocarbons), HCFCs (hydrofluorocarbons) and other ozone depleting substances

None of the substances included in the Montreal Protocol annex A, B, or C is used in Chip PC's manufacturing plants.

#### F2. ADDITIONAL MATERIALS INFORMATION

- The cables may use PVC as an insulating material to ensure product safety
- The case material is ABS+PC
- This product does not contain one or more mercury bulbs

## F3. FLAME RETARDANTS USED IN MECHANICAL PLASTIC PARTS > 25 GRAMS AND PRINTED WIRING BOARDS

Part	Flame Retardant	ISO 1043-4	ISO 11469
Mechanical Plastic Parts > 25 grams PC+ABS	Triaryl Phosphate Ester	FR(40)	ISO 11469
Printed Wiring Board	TBBPA	FR(16)	N/A
Mechanical Plastic Parts > 25 grams ABS	None	None	ISO 11469

#### F4. COMPLIANCE WITH ROHS - LEAD-FREE INFORMATION

This product was redesigned to comply with the European Union's Directive 2002/95/EC, Restrictions of Hazardous Substances ("RoHS" Directive) and similar regulations that may be adopted by other countries. All products manufactured after the 1<sup>st</sup> of January 2006 are fully compliant with the European Union's Directive 2002/95/EC unless written differently on product land will contain only allowed substances.

#### ROHS Declaration

This product does not contain RoHS restricted substances as homogeneous materials:

- a) Greater than quantity limit of 0.1% (1000 PPM) for:
  - 1. Lead (Pb)
  - 2. Mercury
  - 3. Hexavalent Chromium in non-metallic applications (paints, pigments and plastics)
  - 4. Polybrominated Biphenyls (PBB)

<sup>&</sup>lt;sup>2</sup>Waste Handling. Local regulations should be observed when disposing of this product due to the presence of the materials and substances as listed above.



- 5. Polybrominated Diphenyl Ethers (PBDE);
- b) Hexavalent Chromium in metallic applications: Corrosion preventative coatings (conversion coatings) containing Hexavalent Chromium shall not be used in metal parts, components, materials or products. And impurities shall not exceed 0.1% (1000 PPM) in any metallic application;
- c) Greater than quantity limit of 0.01% (100 PPM) for:
  - 1. Cadmium.

## **G. PACKAGING**

No CFCs (chlorofluorocarbons), HCFCs (hydrofluorocarbons) or other ozone depleting substances are used in packaging material. Chromium, lead, mercury, or cadmium are not intentionally added to packaging materials and are not present in a cumulative concentration greater than 100 ppm as incidental impurities. Printed user documentation is bleached in a chlorine-free process. (Europe Only)

Criteria	Yes / No		
No halogenated plastics or polymers are used for packaging material	Yes		
Complies with the EU Directive 94/ 62/ EEC			
Depending on your point of purchase, packaging materials are labeled in accordance with DIN 6120 –     "Marking of packing materials and packages for their recycling"	Yes		

#### H. BATTERIES

This product does not contain any batteries

#### I. EXTERNAL POWER SUPPLY (OPTIONAL)

Chip PC supplies its products, when applicable, with a power supply compliant with all needed regulatory compliance standards, such as UL-listed, Tuv-GS, FCC, CE etc.

## J. DESIGN FOR ENVIRONMENT

Visit www.chippc.com/environment for more information.

#### **K. LONGEVITY AND UPGRADING**

All Chip PC products are designed for easy assembly, disassembly, and disposal. To extend the life of your Chip PC product, you can install or upgrade certain software components (e.g., image, Plug-Ins). As Chip PC products are built for long life, products are in general not designed for repair.

## L. RECYCLABLES

For recyclables, this system incorporates the following design guidelines:

Minimal use of non-separable connections, such as gluing and welding between different materials.	Yes
Minimal use of composite structure materials.	Yes
Painting/varnishing plastic material has been avoided.	Yes
Mechanical plastic parts greater than 100 grams consist of one material or of easily separable materials.	Yes

# M. RECYCLING/ END-OF-LIFE SERVICE INFORMATION

Take back and recycling services are offered for this product in certain countries. If you want to dispose your product, contact Chip PC reseller or sales office for instructions.

## N. CHIP PC CORPORATE ENVIRONMENTAL INFORMATION

The following information is available at <a href="www.chippc.com/environment">www.chippc.com/environment</a>:

- Corporate Environmental Policy
- Environmental Reports
- ISO 14001 certified environmental management systems

Version #: 0905